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(54) [Title of the Invention] RECYCLABLE LAMINATE AND PRINTED CIRCUIT BOARD USING IT

(57) [Abstract]

[Object] The object of the present invention is to provide a laminate and a printed circuit board which are recyclable and have good heat resistance.

[Structure] A recyclable laminate consisting of an electrically insulating layer and an electrically conductive layer, wherein a synthetic resin soluble in a solvent and having a glass transition temperature of no less than 260°C is used as a synthetic resin component of the electrically insulating layer. A printed circuit board using the laminate. Examples of synthetic resin include polyimides and fluorinated polyimides, in particular, polyimides using 2,2'-bis(trifluoromethyl)-4,4'-diaminobiphenyl as a diamine component.

[Effect] Recyclability makes it possible to protect environment and conserve natural resources.